

# TP3054, TP3057 "Enhanced" Serial Interface CODEC/Filter COMBO® Family

## **General Description**

The TP3054, TP3057 family consists of  $\mu$ -law and A-law monolithic PCM CODEC/filters utilizing the A/D and D/A conversion architecture shown in *Figure 1*, and a serial PCM interface. The devices are fabricated using National's advanced double-poly CMOS process (microCMOS).

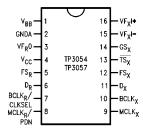
The encode portion of each device consists of an input gain adjust amplifier, an active RC pre-filter which eliminates very high frequency noise prior to entering a switched-capacitor band-pass filter that rejects signals below 200 Hz and above 3400 Hz. Also included are auto-zero circuitry and a companding coder which samples the filtered signal and encodes it in the companded  $\mu\text{-law}$  or A-law PCM format. The decode portion of each device consists of an expanding decoder, which reconstructs the analog signal from the companded  $\mu$ -law or A-law code, a low-pass filter which corrects for the sin x/x response of the decoder output and rejects signals above 3400 Hz followed by a single-ended power amplifier capable of driving low impedance loads. The devices require two 1.536 MHz, 1.544 MHz or 2.048 MHz transmit and receive master clocks, which may be asynchronous; transmit and receive bit clocks, which may vary from 64 kHz to 2.048 MHz; and transmit and receive frame sync pulses. The timing of the frame sync pulses and PCM data is compatible with both industry standard formats.

## **Features**

- Complete CODEC and filtering system (COMBO) including:
  - Transmit high-pass and low-pass filtering
  - Receive low-pass filter with sin x/x correction
  - Active RC noise filters
  - μ-law or A-law compatible COder and DECoder
  - Internal precision voltage reference
  - Serial I/O interface
  - Internal auto-zero circuitry
- μ-law, 16-pin—TP3054
- A-law, 16-pin—TP3057
- Designed for D3/D4 and CCITT applications
- ±5V operation
- Low operating power—typically 50 mW
- Power-down standby mode—typically 3 mW
- Automatic power-down
- TTL or CMOS compatible digital interfaces
- Maximizes line interface card circuit density
- Dual-In-Line or surface mount packages
- See also AN-370, "Techniques for Designing with CODEC/Filter COMBO Circuits"

## **Connection Diagrams**

## **Dual-In-Line Package**



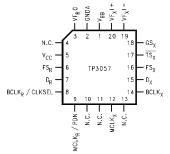
TL/H/5510-1

Top View
Order Number TP3054J or TP3057J
See NS Package Number J16A

Order Number TP3054N or TP3057N See NS Package Number N16A

Order Number TP3054WM or TP3057WM See NS Package Number M16B

## Plastic Chip Carriers



TL/H/5510-10

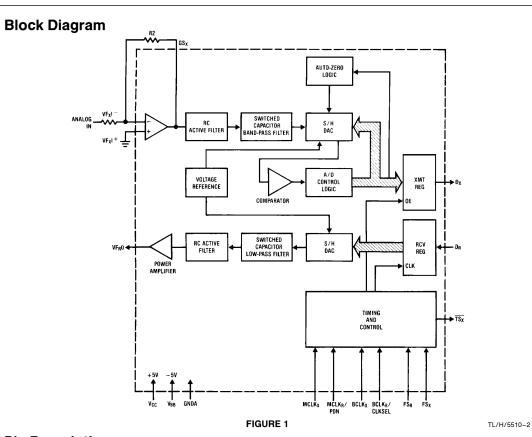
Top View

Order Number TP3057V See NS Package Number V20A

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**Pin Description** 

Symbol	Function	Symbol	Function
$V_{BB}$	Negative power supply pin. $V_{BB} = -5V \pm 5\%$ .		should be synchronous with $MCLK_X$ for best performance. When $MCLK_R$ is connected continu-
GNDA	Analog ground. All signals are referenced to this pin.		ously low, $\mathrm{MCLK}_{X}$ is selected for all internal timing. When $\mathrm{MCLK}_{R}$ is connected continuously
VF <sub>R</sub> O	Analog output of the receive power amplifier.	MCLKX	high, the device is powered down.  Transmit master clock. Must be 1.536 MHz,
V <sub>CC</sub>	Positive power supply pin. $V_{CC} = +5V \pm 5\%$ .		1.544 MHz or 2.048 MHz. May be asynchronous with MCLK <sub>R</sub> . Best performance is realized from synchronous operation.
FS <sub>R</sub>	Receive frame sync pulse which enables $BCLK_R$ to shift PCM data into $D_R$ . $FS_R$ is an 8 kHz pulse train. See <i>Figures 2</i> and 3 for timing details.	FS <sub>X</sub>	Transmit frame sync pulse input which enables $BCLK_X$ to shift out the PCM data on $D_X$ . $FS_X$ is an 8 kHz pulse train, see <i>Figures 2</i> and 3 for timing details.
$D_{R}$	Receive data input. PCM data is shifted into $D_R$ following the $FS_R$ leading edge.	BCLKX	The bit clock which shifts out the PCM data on D <sub>x</sub> . May vary from 64 kHz to 2.048 MHz, but
BCLK <sub>R</sub> /CLKSEL	The bit clock which shifts data into D <sub>R</sub> af-		must be synchronous with MCLK <sub>X</sub> .
	ter the FS <sub>R</sub> leading edge. May vary from 64 kHz to 2.048 MHz. Alternatively, may be a logic input which selects either	$D_X$	The TRI-STATE® PCM data output which is enabled by $FS_X$ .
	1.536 MHz/1.544 MHz or 2.048 MHz for master clock in synchronous mode and	TS <sub>X</sub>	Open drain output which pulses low during the encoder time slot.
	$BCLK_X$ is used for both transmit and receive directions (see Table I).	GS <sub>X</sub>	Analog output of the transmit input amplifier. Used to externally set gain.
MCLK <sub>R</sub> /PDN	Receive master clock. Must be	$VF_XI^-$	Inverting input of the transmit input amplifier.
	1.536 MHz, 1.544 MHz or 2.048 MHz. May be asynchronous with MCLK <sub>X</sub> , but	$VF_XI^+$	Non-inverting input of the transmit input amplifier.

## **Functional Description**

#### POWER-UP

When power is first applied, power-on reset circuitry initializes the COMBO and places it into a power-down state. All non-essential circuits are deactivated and the  $D_X$  and  $VF_RO$  outputs are put in high impedance states. To power-up the device, a logical low level or clock must be applied to the  $MCLK_R/PDN$  pin  $and\ FS_X$  and/or  $FS_R$  pulses must be present. Thus, 2 power-down control modes are available. The first is to pull the  $MCLK_R/PDN$  pin high; the alternative is to hold both  $FS_X$  and  $FS_R$  inputs continuously low—the device will power-down approximately 1 ms after the last  $FS_X$  or  $FS_R$  pulse. Power-up will occur on the first  $FS_X$  or  $FS_R$  pulse. The TRI-STATE PCM data output,  $D_X$ , will remain in the high impedance state until the second  $FS_Y$  pulse.

#### SYNCHRONOUS OPERATION

For synchronous operation, the same master clock and bit clock should be used for both the transmit and receive directions. In this mode, a clock must be applied to MCLK\_X and the MCLK\_R/PDN pin can be used as a power-down control. A low level on MCLK\_R/PDN powers up the device and a high level powers down the device. In either case, MCLK\_X will be selected as the master clock for both the transmit and receive circuits. A bit clock must also be applied to BCLK\_X and the BCLK\_R/CLKSEL can be used to select the proper internal divider for a master clock of 1.536 MHz, 1.544 MHz or 2.048 MHz. For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame.

With a fixed level on the BCLK $_{\rm R}$ /CLKSEL pin, BCLK $_{\rm X}$  will be selected as the bit clock for both the transmit and receive directions. Table 1 indicates the frequencies of operation which can be selected, depending on the state of BCLK $_{\rm R}$ /CLKSEL. In this synchronous mode, the bit clock, BCLK $_{\rm X}$ , may be from 64 kHz to 2.048 MHz, but must be synchronous with MCLK $_{\rm X}$ .

Each FS $_{\rm X}$  pulse begins the encoding cycle and the PCM data from the previous encode cycle is shifted out of the enabled D $_{\rm X}$  output on the positive edge of BCLK $_{\rm X}$ . After 8 bit clock periods, the TRI-STATE D $_{\rm X}$  output is returned to a high impedance state. With an FS $_{\rm R}$  pulse, PCM data is latched via the D $_{\rm R}$  input on the negative edge of BCLK $_{\rm X}$  (or BCLK $_{\rm R}$  if running). FS $_{\rm X}$  and FS $_{\rm R}$  must be synchronous with MCLK $_{\rm X/R}$ .

**TABLE I. Selection of Master Clock Frequencies** 

BCLK <sub>R</sub> /CLKSEL	Master Clock Frequency Selected							
	TP3057	TP3054						
Clocked	2.048 MHz	1.536 MHz or						
		1.544 MHz						
0	1.536 MHz or	2.048 MHz						
	1.544 MHz							
1	2.048 MHz	1.536 MHz or						
		1.544 MHz						

#### ASYNCHRONOUS OPERATION

For asynchronous operation, separate transmit and receive clocks may be applied. MCLKX and MCLKR must be 2.048 MHz for the TP3057, or 1.536 MHz, 1.544 MHz for the TP3054, and need not be synchronous. For best transmission performance, however, MCLK<sub>R</sub> should be synchronous with MCLKX, which is easily achieved by applying only static logic levels to the MCLK<sub>R</sub>/PDN pin. This will automatically connect MCLKX to all internal MCLKR functions (see Pin Description). For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame. FS<sub>X</sub> starts each encoding cycle and must be synchronous with MCLKX and BCLKX. FSR starts each decoding cycle and must be synchronous with BCLK<sub>B</sub>. BCLK<sub>B</sub> must be a clock, the logic levels shown in Table 1 are not valid in asynchronous mode.  $\mathsf{BCLK}_X$  and  $\mathsf{BCLK}_R$  may operate from 64 kHz to 2.048 MHz.

#### SHORT FRAME SYNC OPERATION

The COMBO can utilize either a short frame sync pulse or a long frame sync pulse. Upon power initialization, the device assumes a short frame mode. In this mode, both frame sync pulses,  $FS_X$  and  $FS_R$ , must be one bit clock period long, with timing relationships specified in  $\mathit{Figure 2}$ . With  $FS_X$  high during a falling edge of BCLK\_X, the next rising edge of BCLK\_X enables the D\_X TRI-STATE output buffer, which will output the sign bit. The following seven rising edges clock out the remaining seven bits, and the next falling edge disables the D\_X output. With FS\_R high during a falling edge of BCLK\_R (BCLK\_X in synchronous mode), the next falling edge of BCLK\_R (Bclck\_x in the sign bit. The following seven falling edges latch in the seven remaining bits. All four devices may utilize the short frame sync pulse in synchronous or asynchronous operating mode.

### LONG FRAME SYNC OPERATION

To use the long frame mode, both the frame sync pulses, FS<sub>x</sub> and FS<sub>B</sub>, must be three or more bit clock periods long, with timing relationships specified in Figure 3. Based on the transmit frame sync, FSX, the COMBO will sense whether short or long frame sync pulses are being used. For 64 kHz operation, the frame sync pulse must be kept low for a minimum of 160 ns. The  $D_X$  TRI-STATE output buffer is enabled with the rising edge of  $FS_X$  or the rising edge of  $BCLK_X$ , whichever comes later, and the first bit clocked out is the sign bit. The following seven BCLKx rising edges clock out the remaining seven bits. The  $D_{\mbox{\scriptsize X}}$  output is disabled by the falling  $BCLK_X$  edge following the eighth rising edge, or by FS<sub>X</sub> going low, whichever comes later. A rising edge on the receive frame sync pulse, FSR, will cause the PCM data at D<sub>R</sub> to be latched in on the next eight falling edges of BCLK<sub>R</sub> (BCLK<sub>X</sub> in synchronous mode). All four devices may utilize the long frame sync pulse in synchronous or asynchronous

In applications where the LSB bit is used for signalling with FSR two bit clock periods long, the decoder will interpret the lost LSB as "1/2" to minimize noise and distortion.

## Functional Description (Continued)

#### TRANSMIT SECTION

The transmit section input is an operational amplifier with provision for gain adjustment using two external resistors, see Figure 4. The low noise and wide bandwidth allow gains in excess of 20 dB across the audio passband to be realized. The op amp drives a unity-gain filter consisting of RC active pre-filter, followed by an eighth order switched-capacitor bandpass filter clocked at 256 kHz. The output of this filter directly drives the encoder sample-and-hold circuit. The A/D is of companding type according to  $\mu$ -law (TP3054) or A-law (TP3057) coding conventions. A precision voltage reference is trimmed in manufacturing to provide an input overload (t<sub>MAX</sub>) of nominally 2.5V peak (see table of Transmission Characteristics). The FS<sub>X</sub> frame sync pulse controls the sampling of the filter output, and then the successive-approximation encoding cycle begins. The 8-bit code is then loaded into a buffer and shifted out through DX at the next FSX pulse. The total encoding delay will be approximately 165  $\mu s$  (due to the transmit filter) plus 125  $\mu s$  (due to encoding delay), which totals 290  $\,\mu s.$  Any offset voltage due to the filters or comparator is cancelled by sign bit integration.

#### RECEIVE SECTION

The receive section consists of an expanding DAC which drives a fifth order switched-capacitor low pass filter clocked at 256 kHz. The decoder is A-law (TP3057) or  $\mu$ -law (TP3054) and the 5th order low pass filter corrects for the sin x/x attenuation due to the 8 kHz sample/hold. The filter is then followed by a 2nd order RC active post-filter/power amplifer capable of driving a  $600\Omega$  load to a level of 7.2 dBm. The receive section is unity-gain. Upon the occurrence of FSR, the data at the DR input is clocked in on the falling edge of the next eight BCLKR (BCLKx) periods. At the end of the decoder time slot, the decoding cycle begins, and 10  $\mu$ s later the decoder DAC output is updated. The total decoder delay is  $\sim 10~\mu s$  (decoder update) plus 110  $\mu$ s (filter delay) plus 62.5  $\mu$ s (½ frame), which gives approximately 180  $\mu$ s.

## **Absolute Maximum Ratings**

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

 $V_{CC}$  to GNDA 7V  $V_{BB}$  to GNDA -7V Voltage at any Analog Input

or Output  $V_{CC} + 0.3V$  to  $V_{BB} - 0.3V$ 

Voltage at any Digital Input or

Output  $V_{CC}+0.3V$  to GNDA-0.3V Operating Temperature Range  $-25^{\circ}\mathrm{C}$  to  $+125^{\circ}\mathrm{C}$ 

 $\begin{array}{lll} {\rm Storage\ Temperature\ Range} & -65^{\circ}{\rm C\ to} + 150^{\circ}{\rm C} \\ {\rm Lead\ Temperature\ (Soldering,\ 10\ seconds)} & 300^{\circ}{\rm C} \\ {\rm ESD\ (Human\ Body\ Model)} & 2000{\rm V} \end{array}$ 

Latch-Up Immunity = 100 mA on any Pin

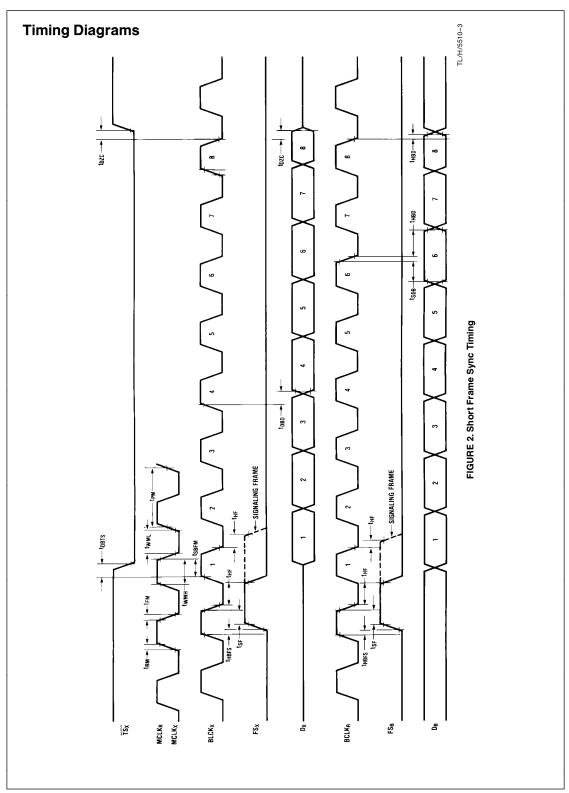
**Electrical Characteristics** Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC} = 5.0V \pm 5\%$ ,  $V_{BB} = -5.0V \pm 5\%$ ;  $T_A = 0^{\circ}C$  to  $70^{\circ}C$  by correlation with 100% electrical testing at  $T_A = 25^{\circ}C$ . All other limits are assured by correlation with other production tests and/or product design and characterization. All signals referenced to GNDA. Typicals specified at  $V_{CC} = 5.0V$ ,  $V_{BB} = -5.0V$ ,  $T_A = 25^{\circ}C$ .

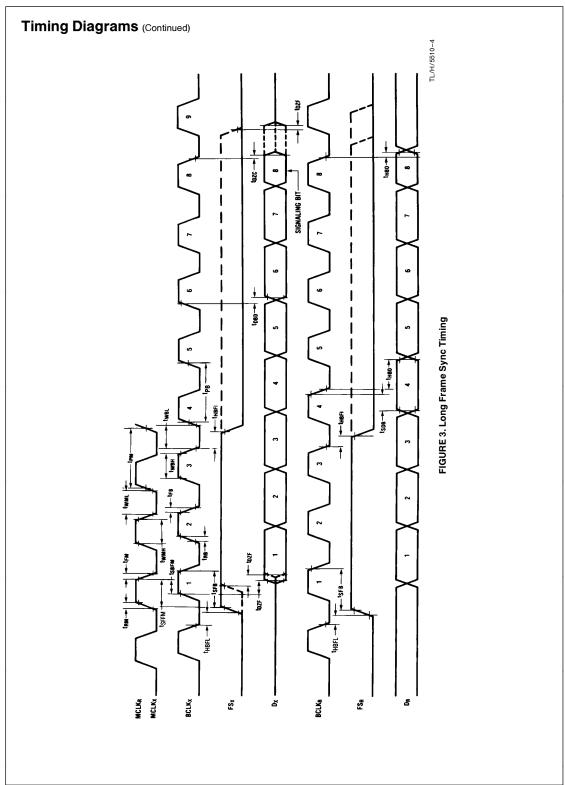
Symbol	Parameter	Conditions	Min	Тур	Max	Units
DIGITAL IN	TERFACE					
$V_{IL}$	Input Low Voltage				0.6	٧
$V_{IH}$	Input High Voltage	2.2				٧
V <sub>OL</sub>	Output Low Voltage	$\begin{array}{l} D_{X}, \ I_{L} = 3.2 \text{ mA} \\ SIG_{P}, \ I_{L} = 1.0 \text{ mA} \\ \hline \overline{TS}_{X}, \ I_{L} = 3.2 \text{ mA}, \text{ Open Drain} \end{array}$			0.4 0.4 0.4	V V V
V <sub>OH</sub>	Output High Voltage	$D_X$ , $I_H$ = $-3.2$ mA SIG $_R$ , $I_H$ = $-1.0$ mA	2.4 2.4			V V
I <sub>IL</sub>	Input Low Current	$GNDA \! \leq \! V_{IN} \! \leq \! V_{IL},  All   Digital   Inputs$	-10		10	μΑ
I <sub>IH</sub>	Input High Current	$V_{IH} \le V_{IN} \le V_{CC}$	-10		10	μΑ
l <sub>OZ</sub>	Output Current in High Impedance State (TRI-STATE)	$D_X$ , $GNDA \le V_O \le V_{CC}$	<b>-10</b>		10	μΑ
ANALOG IN	NTERFACE WITH TRANSMIT INPUT	AMPLIFIER (ALL DEVICES)				
I <sub>I</sub> XA	Input Leakage Current	$-2.5V \le V \le +2.5V$ , $VF_XI^+$ or $VF_XI^-$	<b>-200</b>		200	nA
R <sub>I</sub> XA	Input Resistance	$-2.5V \le V \le +2.5V$ , VF <sub>X</sub> I <sup>+</sup> or VF <sub>X</sub> I <sup>-</sup>	10			$M\Omega$
R <sub>O</sub> XA	Output Resistance	Closed Loop, Unity Gain		1	3	Ω
R <sub>L</sub> XA	Load Resistance	GS <sub>X</sub>	10			kΩ
$C_LXA$	Load Capacitance	GS <sub>X</sub>			50	pF
V <sub>O</sub> XA	Output Dynamic Range	$GS_X$ , $R_L \ge 10 \text{ k}\Omega$	<b>-2.8</b>		2.8	V
A <sub>V</sub> XA	Voltage Gain	VF <sub>X</sub> I <sup>+</sup> to GS <sub>X</sub>	5000			V/V
F <sub>U</sub> XA	Unity Gain Bandwidth		1	2		MHz
V <sub>OS</sub> XA	Offset Voltage		-20		20	mV
$V_{CM}XA$	Common-Mode Voltage	CMRRXA > 60 dB	-2.5		2.5	٧
CMRRXA	Common-Mode Rejection Ratio	DC Test	60			dB
PSRRXA	Power Supply Rejection Ratio	DC Test	60			dB
ANALOG IN	NTERFACE WITH RECEIVE FILTER (	ALL DEVICES)		•		
R <sub>O</sub> RF	Output Resistance	Pin VF <sub>R</sub> O		1	3	Ω
$R_LRF$	Load Resistance	$VF_RO = \pm 2.5V$	600			Ω
C <sub>L</sub> RF	Load Capacitance				500	pF
VOS <sub>R</sub> O	Output DC Offset Voltage		-200		200	mV
POWER DIS	SSIPATION (ALL DEVICES)					
I <sub>CC</sub> 0	Power-Down Current	No Load (Note)		0.5	1.5	mA
I <sub>BB</sub> 0	Power-Down Current	No Load (Note)		0.05	0.3	mA
I <sub>CC</sub> 1	Power-Up Active Current	No Load		5.0	9.0	mA
I <sub>BB</sub> 1	Power-Up Active Current	No Load		5.0	9.0	mA

Note:  $I_{\text{CC0}}$  and  $I_{\text{BB0}}$  are measured after first achieving a power-up state.

**Timing Specifications** Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC} = 5.0V \pm 5\%$ ,  $V_{BB} = -5.0V \pm 5\%$ ;  $T_A = 0^{\circ}\text{C}$  to 70°C by correlation with 100% electrical testing at  $T_A = 25^{\circ}\text{C}$ . All other limits are assured by correlation with other production tests and/or product design and characterization. All signals referenced to GNDA. Typicals specified at  $V_{CC} = 5.0V$ ,  $V_{BB} = -5.0V$ ,  $T_A = 25^{\circ}\text{C}$ . All timing parameters are measured at  $V_{OH} = 2.0V$  and  $V_{OL} = 0.7V$ . See Definitions and Timing Conventions section for test methods information.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
1/t <sub>PM</sub>	Frequency of Master Clocks	Depends on the Device Used and the $\mathrm{BCLK}_R/\mathrm{CLKSEL}$ Pin. $\mathrm{MCLK}_X$ and $\mathrm{MCLK}_R$		1.536 1.544 <b>2.048</b>		MHz MHz MHz
t <sub>RM</sub>	Rise Time of Master Clock	$MCLK_X$ and $MCLK_R$			50	ns
$t_{\text{FM}}$	Fall Time of Master Clock	$MCLK_X$ and $MCLK_R$			50	ns
t <sub>PB</sub>	Period of Bit Clock		485	488	15725	ns
t <sub>RB</sub>	Rise Time of Bit Clock	BCLK <sub>X</sub> and BCLK <sub>R</sub>			50	ns
t <sub>FB</sub>	Fall Time of Bit Clock	BCLK <sub>X</sub> and BCLK <sub>R</sub>			50	ns
t <sub>WMH</sub>	Width of Master Clock High	$MCLK_X$ and $MCLK_R$	160			ns
t <sub>WML</sub>	Width of Master Clock Low	$MCLK_X$ and $MCLK_R$	160			ns
t <sub>SBFM</sub>	Set-Up Time from $BCLK_X$ High to $MCLK_X$ Falling Edge	First Bit Clock after the Leading Edge of $FS_X$	100			ns
t <sub>SFFM</sub>	Set-Up Time from $FS_X$ High to $MCLK_X$ Falling Edge	Long Frame Only	100			ns
t <sub>WBH</sub>	Width of Bit Clock High	V <sub>IH</sub> =2.2V	160			ns
t <sub>WBL</sub>	Width of Bit Clock Low	V <sub>IL</sub> =0.6V	160			ns
t <sub>HBFL</sub>	Holding Time from Bit Clock Low to Frame Sync	Long Frame Only	0			ns
t <sub>HBFS</sub>	Holding Time from Bit Clock High to Frame Sync	Short Frame Only	0			ns
t <sub>SFB</sub>	Set-Up Time from Frame Sync to Bit Clock Low	Long Frame Only	80			ns
t <sub>DBD</sub>	Delay Time from BCLK <sub>X</sub> High to Data Valid	Load = 150 pF plus 2 LSTTL Loads	0		140	ns
t <sub>DBTS</sub>	Delay Time to TS <sub>X</sub> Low	Load = 150 pF plus 2 LSTTL Loads			140	ns
t <sub>DZC</sub>	Delay Time from BCLK <sub>X</sub> Low to Data Output Disabled	C <sub>L</sub> =0 pF to 150 pF	50		165	ns
t <sub>DZF</sub>	Delay Time to Valid Data from $FS_X$ or $BCLK_X$ , Whichever Comes Later	$C_L$ =0 pF to 150 pF	20		165	ns
t <sub>SDB</sub>	Set-Up Time from $D_R$ Valid to $BCLK_{R/X}$ Low		50			ns
t <sub>HBD</sub>	Hold Time from $\operatorname{BCLK}_{R/X}$ Low to $\operatorname{D}_R$ Invalid		50			ns
t <sub>SF</sub>	Set-Up Time from $FS_{X/R}$ to $BCLK_{X/R}$ Low	Short Frame Sync Pulse (1 Bit Clock Period Long)	50			ns
t <sub>HF</sub>	Hold Time from $BCLK_{X/R}$ Low to $FS_{X/R}$ Low	Short Frame Sync Pulse (1 Bit Clock Period Long)	100			ns
t <sub>HBFI</sub>	Hold Time from 3rd Period of Bit Clock Low to Frame Sync (FS <sub>X</sub> or FS <sub>R</sub> )	Long Frame Sync Pulse (from 3 to 8 Bit Clock Periods Long)	100			ns
t <sub>WFL</sub>	Minimum Width of the Frame Sync Pulse (Low Level)	64k Bit/s Operating Mode	160			ns





**Transmission Characteristics** Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC}=5.0V\pm5\%$ ,  $V_{BB}=-5.0V\pm5\%$ ;  $T_A=0^{\circ}C$  to  $70^{\circ}C$  by correlation with 100% electrical testing at  $T_A=25^{\circ}C$ . All other limits are assured by correlation with other production tests and/or product design and characterization. GNDA = 0V, f = 1.02 kHz,  $V_{IN}=0$  dBm0, transmit input amplifier connected for unity gain non-inverting. Typicals specified at  $V_{CC}=5.0V$ ,  $V_{BB}=-5.0V$ ,  $V_{AB}=25^{\circ}C$ .

Symbol	Parameter	Conditions	Min	Тур	Max	Units
AMPLITU	DE RESPONSE					
	Absolute Levels (Definition of Nominal Gain)	Nominal 0 dBm0 Level is 4 dBm (600 $\Omega$ ) 0 dBm0		1.2276		Vrms
t <sub>MAX</sub>	Virtual Decision Valve Defined Per CCITT Rec. G711	Max Overload Level TP3054 (3.17 dBm0) TP3057 (3.14 dBm0)		2.501 2.492		V <sub>PK</sub>
G <sub>XA</sub>	Transmit Gain, Absolute	$T_A$ = 25°C, $V_{CC}$ = 5V, $V_{BB}$ = $-$ 5V Input at $GS_X$ = 0 dBm0 at 1020 Hz TP3054/57	-0.15		0.15	dB
G <sub>XR</sub>	Transmit Gain, Relative to G <sub>XA</sub>	f=16 Hz f=50 Hz f=60 Hz f=200 Hz f=300 Hz-3000 Hz f=3300 Hz f=3400 Hz f=4000 Hz f=4600 Hz and Up, Measure Response from 0 Hz to 4000 Hz	-1.8 -0.15 -0.35 -0.7		-40 -30 -26 -0.1 0.15 0.05 0 -14 -32	dB dB dB dB dB dB dB
G <sub>XAT</sub>	Absolute Transmit Gain Variation with Temperature	Relative to G <sub>XA</sub>	-0.1		0.1	dB
G <sub>XAV</sub>	Absolute Transmit Gain Variation with Supply Voltage	Relative to G <sub>XA</sub>	-0.05		0.05	dB
G <sub>XRL</sub>	Transmit Gain Variations with Level	Sinusoidal Test Method Reference Level = $-10$ dBm0 VF <sub>X</sub> I + = $-40$ dBm0 to $+3$ dBm0 VF <sub>X</sub> I + = $-50$ dBm0 to $-40$ dBm0 VF <sub>X</sub> I + = $-55$ dBm0 to $-50$ dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB dB dB
G <sub>RA</sub>	Receive Gain, Absolute	T <sub>A</sub> =25°C, V <sub>CC</sub> =5V, V <sub>BB</sub> =-5V Input=Digital Code Sequence for 0 dBm0 Signal at 1020 Hz TP3054/57	-0.15		0.15	dB
G <sub>RR</sub>	Receive Gain, Relative to G <sub>RA</sub>	f=0 Hz to 3000 Hz f=3300 Hz f=3400 Hz f=4000 Hz	-0.15 -0.35 -0.7		0.15 0.05 0 - 14	dB dB dB dB
G <sub>RAT</sub>	Absolute Receive Gain Variation with Temperature	Relative to G <sub>RA</sub>	-0.1		0.1	dB
G <sub>RAV</sub>	Absolute Receive Gain Variation with Supply Voltage	Relative to G <sub>RA</sub>	-0.05		0.05	dB
G <sub>RRL</sub>	Receive Gain Variations with Level	Sinusoidal Test Method; Reference Input PCM Code Corresponds to an Ideally Encoded PCM Level = -40 dBm0 to +3 dBm0 = -50 dBm0 to -40 dBm0 = -55 dBm0 to -50 dBm0	- 0.2 - 0.4 - 1.2		0.2 0.4 1.2	dB dB dB
V <sub>RO</sub>	Receive Output Drive Level	$R_L = 600\Omega$	-2.5		2.5	V

**Transmission Characteristics** (Continued) Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC}=5.0V\pm5\%$ ,  $V_{BB}=-5.0V\pm5\%$ ;  $T_A=0^{\circ}C$  to  $70^{\circ}C$  by correlation with 100% electrical testing at  $T_A=25^{\circ}C$ . All other limits are assured by correlation with other production tests and/or product design and characterization. GNDA = 0V, f = 1.02 kHz,  $V_{IN}=0$  dBm0, transmit input amplifier connected for unity gain non-inverting. Typicals specified at  $V_{CC}=5.0V$ ,  $V_{BB}=-5.0V$ ,  $V_{AB}=25^{\circ}C$ .

Symbol	Parameter	Conditions	Min	Тур	Max	Units
ENVELOP	E DELAY DISTORTION WITH FREQU	IENCY				
D <sub>XA</sub>	Transmit Delay, Absolute	f=1600 Hz		290	315	μs
D <sub>XR</sub>	Transmit Delay, Relative to D <sub>XA</sub>	f=500 Hz-600 Hz		195	220	μs
All	, , , , , , , , , , , , , , , , , , , ,	f=600 Hz-800 Hz		120	145	μs
		f=800 Hz-1000 Hz		50	75	μs
		f=1000 Hz-1600 Hz		20	40	μs
		f=1600 Hz-2600 Hz		55	75	μs
		f=2600 Hz-2800 Hz		80	105	μs
		f=2800 Hz-3000 Hz		130	155	μs
D <sub>RA</sub>	Receive Delay, Absolute	f=1600 Hz		180	200	μs
D <sub>RR</sub>	Receive Delay, Relative to D <sub>RA</sub>	f=500 Hz-1000 Hz	-40	-25		μs
PHH	Tiocolvo Bolay, Florativo to BRA	f=1000 Hz-1600 Hz	-30	-20		μs
		f=1600 Hz-2600 Hz		70	90	μs
		f=2600 Hz-2800 Hz		100	125	μs
		f=2800 Hz-3000 Hz		145	175	μS
NOISE	<u> </u>	1 2000112-0000112	l	140	170	μ5
N <sub>XC</sub>	Transmit Noise, C Message	TP3054		12	15	dBrnC0
•••	Weighted	11 666 1				delile
N <sub>XP</sub>	Transmit Noise, P Message Weighted	TP3057		-74	<b>-67</b>	dBm0p
N <sub>RC</sub>	Receive Noise, C Message	PCM Code is Alternating Positive				
	Weighted	and Negative Zero — TP3054		8	11	dBrnC(
$N_{RP}$	Receive Noise, P Message	PCM Code Equals Positive				
	Weighted	Zero — TP3057		-82	<b>-79</b>	dBm0p
N <sub>RS</sub>	Noise, Single Frequency	f=0 kHz to 100 kHz, Loop Around			-53	dBm0
		Measurement, $VF_XI^+ = 0 Vrms$				
PPSRX	Positive Power Supply Rejection,	$VF_XI^+ = -50 \text{ dBm0}$				
	Transmit	V <sub>CC</sub> =5.0 V <sub>DC</sub> +100 mVrms				
		f=0 kHz-50 kHz (Note 2)	40			dBC
NPSRX	Negative Power Supply Rejection,	$VF_XI^+ = -50 \text{ dBm0}$				
^	Transmit	$V_{BB} = -5.0 V_{DC} + 100 \text{ mVrms}$				
		f=0 kHz-50 kHz (Note 2)	40			dBC
DDCD_	Positive Power Supply Rejection	, ,				
PPSRR	Positive Power Supply Rejection,	PCM Code Equals Positive Zero				
	Receive	V <sub>CC</sub> =5.0 V <sub>DC</sub> +100 mVrms				
		Measure VF <sub>R</sub> 0	40			-100
		f=0 Hz-4000 Hz	40			dBC
		f=4 kHz-25 kHz	40			dB
		f=25 kHz-50 kHz	36			dB
NPSRR	Negative Power Supply Rejection,	PCM Code Equals Positive Zero				
	Receive	$V_{BB} = -5.0 V_{DC} + 100 \text{ mVrms}$				
		Measure VF <sub>R</sub> 0				
		f=0 Hz-4000 Hz	40			dBC
		f=4 kHz-25 kHz	40			dB
		f=25 kHz-50 kHz	36			dB

**Transmission Characteristics** (Continued) Unless otherwise noted, limits printed in **BOLD** characters are guaranteed for  $V_{CC}=5.0V\pm5\%$ ,  $V_{BB}=-5.0V\pm5\%$ ;  $T_A=0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$  by correlation with 100% electrical testing at  $T_A=25^{\circ}\text{C}$ . All other limits are assured by correlation with other production tests and/or product design and characterization. GNDA = 0V, f = 1.02 kHz,  $V_{IN}=0$  dBm0, transmit input amplifier connected for unity gain non-inverting. Typicals specified at  $V_{CC}=5.0V$ ,  $V_{BB}=-5.0V$ ,  $V_{AB}=25^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	Min	Тур	Max	Units
SOS	Spurious Out-of-Band Signals at the Channel Output	Loop Around Measurement, 0 dBm0, 300 Hz to 3400 Hz Input PCM Code Applied at D <sub>B</sub> .			-30	dB
		4600 Hz-7600 Hz			-30	dB
		7600 Hz-8400 Hz			-40	dB
		8400 Hz-100,000 Hz			-30	dB
DISTORT	ION					
STD <sub>X</sub> STD <sub>R</sub>	Signal to Total Distortion Transmit or Receive Half-Channel	Sinusoidal Test Method (Note 3) Level = 3.0 dBm0 = 0 dBm0 to -30 dBm0 = -40 dBm0 XMT RCV = -55 dBm0 XMT	33 36 29 30 14 15			dBC dBC dBC dBC dBC dBC
$SFD_X$	Single Frequency Distortion, Transmit				<b>-46</b>	dB
SFD <sub>R</sub>	Single Frequency Distortion, Receive				<b>-46</b>	dB
IMD	Intermodulation Distortion	Loop Around Measurement, $VF_X{}^+ = -4$ dBm0 to $-21$ dBm0, Two Frequencies in the Range 300 Hz $-3400$ Hz			-41	dB
CROSSTA	ALK					
CT <sub>X-R</sub>	Transmit to Receive Crosstalk,	f=300 Hz-3400 Hz				
	0 dBm0 Transmit Level	D <sub>R</sub> =Quiet PCM Code		-90	<b>-75</b>	dB
CT <sub>R-X</sub>	Receive to Transmit Crosstalk, 0 dBm0 Receive Level	f = 300 Hz – 3400 Hz, VF <sub>X</sub> I = Multitone (Note 2)		-90	<b>-70</b>	dB

## ENCODING FORMAT AT $D_{\mathsf{X}}$ OUTPUT

	TP3054 μ-Law						(Inc	ludes	TP3 A-L s Ever	_aw	nvers	ion)				
$V_{IN}$ (at $GS_X$ ) = + Full-Scale	1	0	0	0	0	0	0	0	1	0	1	0	1	0	1	0
V <sub>IN</sub> (at GS <sub>X</sub> )=0V	{1 0	1	1	1	1	1	1	1	1 0	1	0	1	0	1	0 0	1
$V_{IN}$ (at $GS_X$ ) = $-$ Full-Scale	0	0	0	0	0	0	0	0	0	0	1	0	1	0	1	0

Note 1: Measured by extrapolation from the distortion test result at  $-50\ \mathrm{dBm0}.$ 

Note 2: PPSRx, NPSRx, and CT<sub>R-X</sub> are measured with a -50 dBm0 activation signal applied to VFxI  $^{+}.$ 

Note 3: Devices are measured using C message weighted filter for  $\mu$ -Law and psophometric weighted filter for A-Law.

## **Applications Information**

#### **POWER SUPPLIES**

While the pins of the TP305X family are well protected against electrical misuse, it is recommended that the standard CMOS practice be followed, ensuring that ground is connected to the device before any other connections are made. In applications where the printed circuit board may be plugged into a "hot" socket with power and clocks already present, an extra long ground pin in the connector should be used.

All ground connections to each device should meet at a common point as close as possible to the GNDA pin. This minimizes the interaction of ground return currents flowing through a common bus impedance. 0.1  $\mu\text{F}$  supply decoupling capacitors should be connected from this common ground point to VCC and VBB, as close to the device as possible.

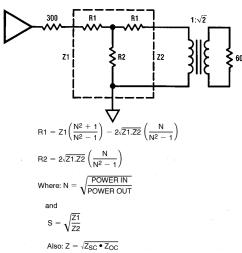
For best performance, the ground point of each CODEC/FILTER on a card should be connected to a common card ground in star formation, rather than via a ground bus.

This common ground point should be decoupled to  $V_{CC}$  and  $V_{BB}$  with 10  $\mu\text{F}$  capacitors.

#### **RECEIVE GAIN ADJUSTMENT**

For applications where a TP305X family CODEC/filter receive output must drive a  $600\Omega$  load, but a peak swing lower than  $\pm 2.5 V$  is required, the receive gain can be easily adjusted by inserting a matched T-pad or  $\pi$ -pad at the output. Table II lists the required resistor values for  $600\Omega$  terminations. As these are generally non-standard values, the equations can be used to compute the attenuation of the closest practical set of resistors. It may be necessary to use unequal values for the R1 or R4 arms of the attenuators to achieve a precise attenuation. Generally it is tolerable to allow a small deviation of the input impedance from nominal while still maintaining a good return loss. For example a 30 dB return loss against  $600\Omega$  is obtained if the output impedance of the attenuator is in the range  $282\Omega$  to  $319\Omega$  (assuming a perfect transformer).

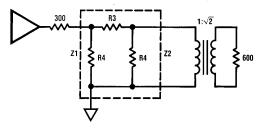
#### **T-Pad Attenuator**



Where  $Z_{SC}$  = impedance with short circuit termination

and  $Z_{OC}$  = impedance with open circuit termination

#### $\pi$ -Pad Attenuator



TL/H/5510-5

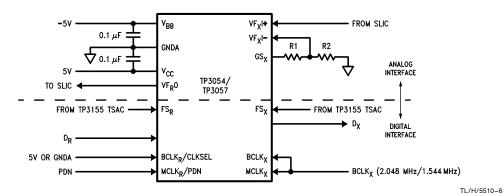
Note: See Application Note 370 for further details.

# **Applications Information** (Continued)

TABLE II. Attentuator Tables for Z1 = Z2 = 300  $\Omega$  (All Values in  $\Omega)$ 

dB	R1	R2	R3	R4
0.1	1.7	26k	3.5	52k
0.2	3.5	13k	6.9	26k
0.3	5.2	8.7k	10.4	17.4k
0.4	6.9	6.5k	13.8	13k
0.5	8.5	5.2k	17.3	10.5k
0.6	10.4	4.4k	21.3	8.7k
0.7	12.1	3.7k	24.2	7.5k
0.8	13.8	3.3k	27.7	6.5k
0.9	15.5	2.9k	31.1	5.8k
1.0	17.3	2.61	34.6	5.2k
2	34.4	1.3k	70	2.6k
3	51.3	850	107	1.8k
4	68	650	144	1.3k
5	84	494	183	1.1k
6	100	402	224	900
7	115	380	269	785
8	379	284	317	698
9	143	244	370	630
10	156	211	427	527
11	168	184	490	535
12	180	161	550	500
13	190	142	635	473
14	200	125	720	450
15	210	110	816	430
16	218	98	924	413
18	233	77	1.17k	386
20	246	61	1.5k	366

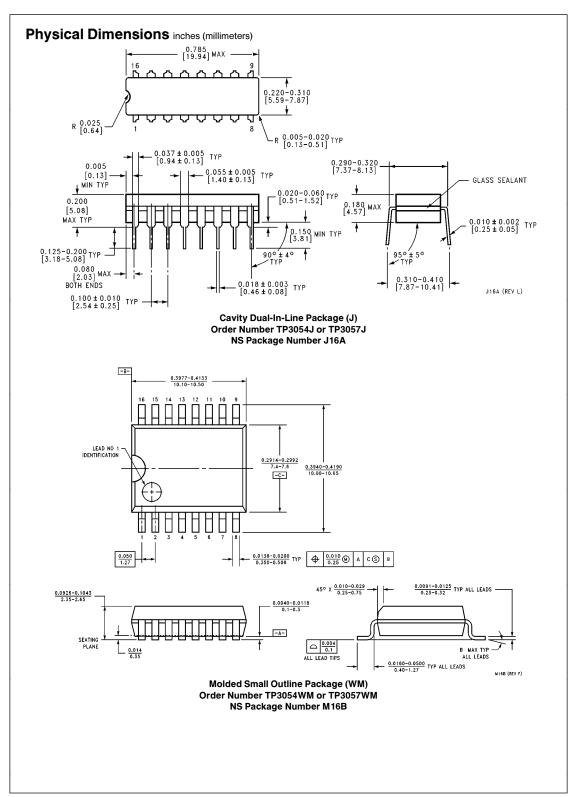
# **Typical Synchronous Application**



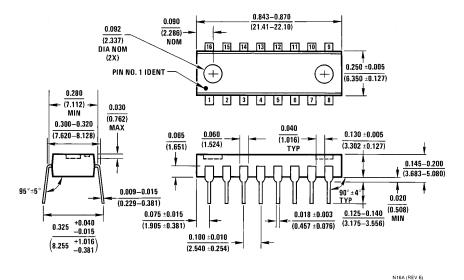
Note 1: XMIT gain =  $20 \times log \left( \frac{R1 + R2}{R2} \right)$  where (R1 + R2) > 10 K $\Omega$ .

FIGURE 4

# **Connection Diagrams** (Continued) Plastic Chip Carrier TP3057 BCLK<sub>R</sub>/CLKSEL TL/H/5510-7 **Top View** Order Number TP3057V See NS Package Number V20A



# Physical Dimensions inches (millimeters) (Continued)



Molded Dual-In-Line Package (N) Order Number TP3054N or TP3057N NS Package Number N16A

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**National Semiconductor** 

National Semiconducto Corporation 1111 West Bardin Road Arlington, TX 76017 Tel: 1(800) 272-9959 Fax: 1(800) 737-7018

**National Semiconductor** Europe

Fax: (+49) 0-180-530 85 86 Fax: (+49) U-18U-35U oo oo Email: onjwege etevm2.nsc.com Deutsch Tel: (+49) 0-180-530 85 85 English Tei: (+49) 0-180-532 78 32 Français Tel: (+49) 0-180-532 93 58 Italiano Tel: (+49) 0-180-534 16 80 National Semiconductor Hong Kong Ltd.
13th Floor, Straight Block,
Ocean Centre, 5 Canton Rd. Tsimshatsui, Kowloon Hong Kong Tel: (852) 2737-1600 Fax: (852) 2736-9960

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Tel: 81-043-299-2309
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